

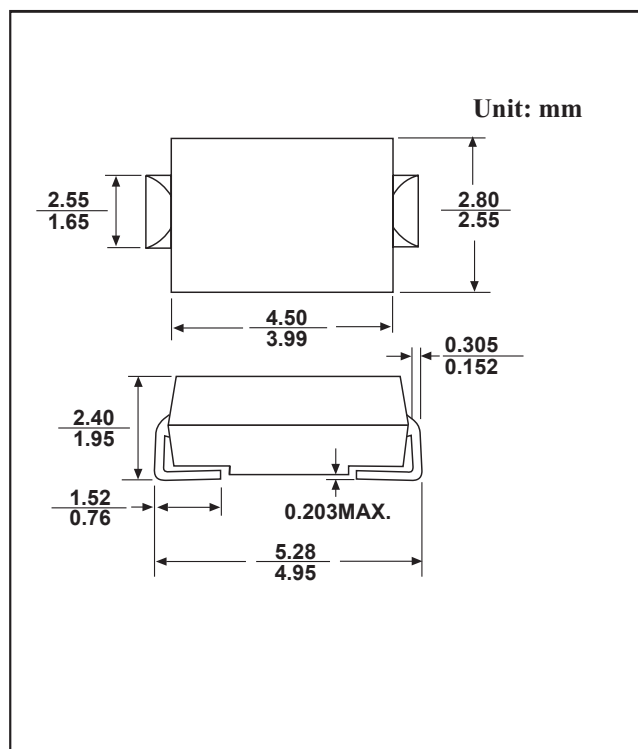
SMA PLASTIC SILICON RECTIFIERS

FEATURES

- The plastic package carries Underwrites Laboratory Flammability Classification 94V-0
- Construction utilizes void-free molded plastic technique
For surface mounted applications
- Built-in strain relief,ideal for automated placement
- High temperature soldering guaranteed:260°C/10 seconds at
- Component in accordance to RoHs 2015/863 andWEEE 2012/19/EU

MECHANICAL DATA

- Case:SMA molded plastic body
- Terminals:Lead solderable per MIL-STD-750,method 2026
- Polarity:Color band denotes cathode end
- Mounting Position:Any



MAXIMUM RATINGS AND CHARACTERISTICS

@ 25°C Ambient Temperature (unless otherwise noted)

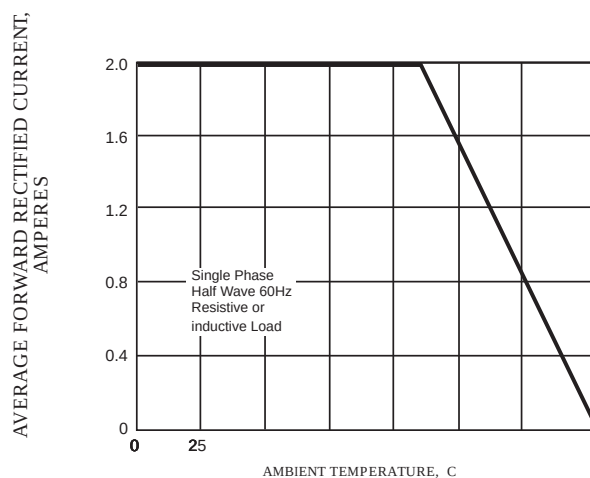
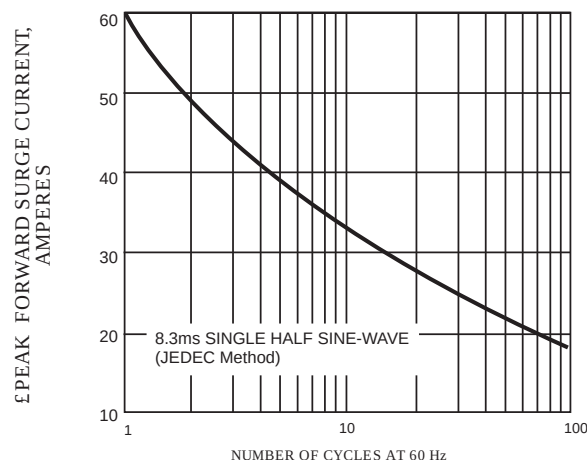
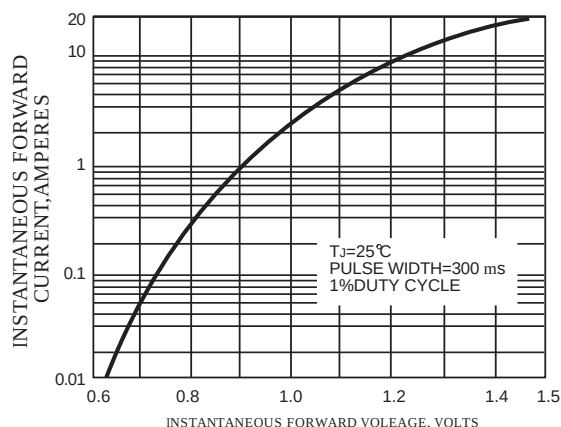
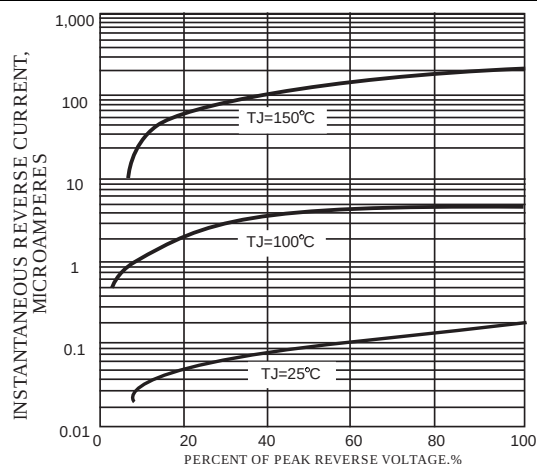
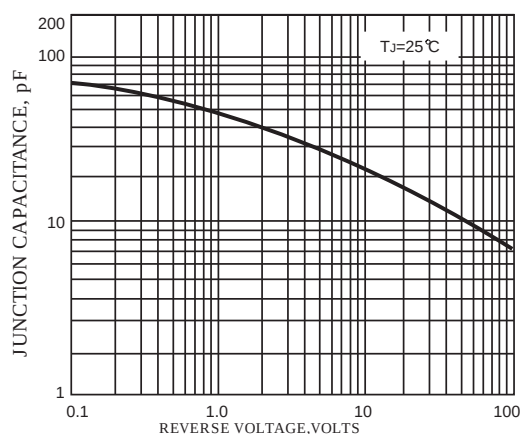
Characteristic	SYMBOLS	S2A	S2B	S2D	S2G	S2J	S2K	S2M	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum DC blocking voltage	V_{DC}								
Maximum RMS Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Maximum average forward rectified current at TL=110℃	$I_{(AV)}$	2.0							A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load(JEDECmethod)	I_{FSM}	60.0							A
Maximum instantaneous forward voltage at 1.0A	V_F	1.0							V
Maximum DC reverse current at rated DC blocking voltage	@TA=25℃	5.0							μ A
	@TA=100℃								
Typical junction capacitance (NOTE 1)	C_J	30							pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	50							℃/W
Operating junction and storage temperature range	T_j	-55 to+150							℃

Note:

1.Measured at 1MHz and applied reverse voltage of 4.0V DC.

2.P.C.B. mounted with 0.4x0.4"(10x10mm) copper pad areas

RATINGS AND CHARACTERISTIC CURVES

FIG. 1- FORWARD CURRENT DERATING CURVE

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

FIG. 4-TYPICAL REVERSE CHARACTERISTICS

FIG. 5-TYPICAL JUNCTION CAPACITANCE

FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE
